

Quarterly Reliability Monitoring Results

Quarters: Q3/2021 to Q4/2022

Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory		User Part Number PESD3V3S2UT-Q Part Description													
											Nexperia DHAM	Protection			
									Assembly reliability labs		SMD package				
Based on AEC-Q101 Test		Test Conditions	Duration	# Lots	# Quantity	# Rejects									
	TEST														
	Pre- and Post-Stress														
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below									
		JESD22-A113													
		Bake Tamb = 125 °C	24 hours												
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours												
# A1	Preconditioning	Reflow soldering	3 cycles	438	24630	0									
		MIL-STD-750-1													
	HTRB	M1038 Method A													
		Tj = Tjmax, Vr = 100% of max. datasheet				_									
# B1	Bias	reverse voltage	1000 hours	166	10040	0									
	T0	JECD22 A104													
# 4.4	TC Temperature Cycling	JESD22-A104 -65 °C to Tjmax, not to exceed 150°C	1000	121	7760	0									
# A4	remperature Cycling	-03 C to Tjillax, flot to exceed 130 C	1000 cycles	131	7760	0									
	UHAST	JESD22-A118													
# A3 or	Unbiased HAST	Tamb = 130 °C, RH = 85 %	96 hours	131	7760	0									
	0.10.0000 1.7.00	JESD22-A102													
	AC	Tamb = 121 °C, RH = 100 %													
# A3 alt	Autoclave	Pressure = 205 kPa (29.7 psia)													
" 715 dic		,													
	H3TRB	JESD22-A101													
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of													
# A2 alt		rated reverse voltage ^[1]	1000 hours	131	7760	0									
		MIL-STD-750 Method 1037													
	IOL	ton = toff, devices powered to insure ΔT_j =													
# A5	Intermittent Operating Life		1000 hours	n.a.	n.a.	n.a.									
	RSH	JESD22-A111													
# C8	Resistance to Solder Heat	260 °C ± 5 °C	10 s	45	1350	0									
	SD														
# C10	Solderability	J-STD-002		111	1110	0									

^[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Protection	10040	0	0,42	2,36E+09

^{© 2023} Nexperia B.V.

All information hereunder is per Nexperia's best knowledge. This document does not provide for any representation or warranty express or implied by Nexperia. In case Nexperia has tested the product, this documentation reflects the outcome of the analysis of the actually tested parts only.

nexperia.com